Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

- Glass Passivated Junctions with Center Gate Fire for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Constructed for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- 300 A Surge Current Capability
- Device Marking: Logo, Device Type, e.g., 2N6504, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
*Peak Repetitive Off–State Voltage(1) (Gate Open, Sine Wave 50 to 60 Hz, T _J = 25 to 125°C)	V _{DRM,} V _{RRM}		Volts
2N6504 2N6505 2N6507 2N6508 2N6509		50 100 400 600 800	
On-State RMS Current (180° Conduction Angles; T _C = 85°C)	IT(RMS)	25	A
Average On-State Current (180° Conduction Angles; T _C = 85°C)	lt(AV)	16	A
Peak Non-repetitive Surge Current 8.3 ms (1/2 Cycle, Sine Wave 60 Hz, T _J = 85°C)	ITSM	300	A
1.5 ms		350	
Forward Peak Gate Power (Pulse Width \leq 1.0 μ s, T _C = 85°C)	PGM	20	Watts
Forward Average Gate Power (t = 8.3 ms, $T_C = 85^{\circ}C$)	PG(AV)	0.5	Watts
Forward Peak Gate Current (Pulse Width \leq 1.0 µs, T _C = 85°C)	IGM	2.0	A
Operating Junction Temperature Range	ТJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

*Indicates JEDEC Registered Data

(1) V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

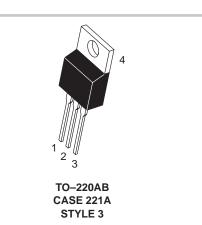


ON Semiconductor

http://onsemi.com

SCRs 25 AMPERES RMS 50 thru 800 VOLTS





Cathode
A se e die
Anode
Gate
Anode

ORDERING INFORMATION

Device	Package	Shipping
2N6504	TO220AB	500/Box
2N6505	TO220AB	500/Box
2N6507	TO220AB	500/Box
2N6508	TO220AB	500/Box
2N6509	TO220AB	500/Box

Preferred devices are recommended choices for future use and best overall value.

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***THERMAL CHARACTERISTICS**

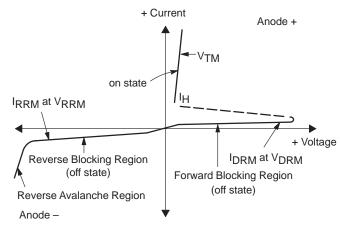
Characteristic			Symbol		Max		Unit	
Thermal Resistance, Junction to Case			R _{θJC}		1.5	c	°C/W	
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds		TL		260		°C		
ELECTRICAL CHARACTERISTICS (T _C = 25°C unlo	ess otherwise not	ed.)						
Characteristic		Symbo	I	Min	Тур	Max	Unit	
OFF CHARACTERISTICS								
* Peak Repetitive Forward or Reverse Blocking Current (V _{AK} = Rated V _{DRM} or V _{RRM} , Gate Open) $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$		IDRM ^{, I} RRM		_		10 2.0	μA mA	
ON CHARACTERISTICS								
* Forward On–State Voltage(1) (I _{TM} = 50 A)		V_{TM}		—	—	1.8	Volts	
*Gate Trigger Current (Continuous dc) (V _{AK} = 12 Vdc, R _L = 100 Ohms)	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	I _{GT} -		_	9.0	30 75	mA	
*Gate Trigger Voltage (Continuous dc) (V _{AK} = 12 Vdc, R _L = 100 Ohms, T _C = -40°C)		V _{GT}		—	1.0	1.5	Volts	
Gate Non-Trigger Voltage (V _{AK} = 12 Vdc, R _L = 100 Ohms, T _J = 125°C)		V _{GD}		0.2	—	_	Volts	
*Holding Current (V _{AK} = 12 Vdc, Initiating Current = 200 mA,	$T_C = 25^{\circ}C$	ΙΗ		_	18	40	mA	
Gate Open)	$T_{C} = -40^{\circ}C$					80		
*Turn-On Time (I _{TM} = 25 A, I _{GT} = 50 mAdc)		^t gt			1.5	2.0	μs	
Turn-Off Time (V _{DRM} = rated voltage) (I_{TM} = 25 A, I_R = 25 A) (I_{TM} = 25 A, I_R = 25 A, T_J = 125°C)		^t q		—	15 35	—	μs	
DYNAMIC CHARACTERISTICS								
Critical Rate of Rise of Off-State Voltage (Gate Open, Rated V _{DRM} , Exponential Waveform)		dv/dt		—	50	—	V/µs	

*Indicates JEDEC Registered Data.

(1) Pulse Test: Pulse Width \leq 300 $\mu s,$ Duty Cycle \leq 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
IRRM	Peak Reverse Blocking Current
VTM	Peak On State Voltage
ΙΗ	Holding Current



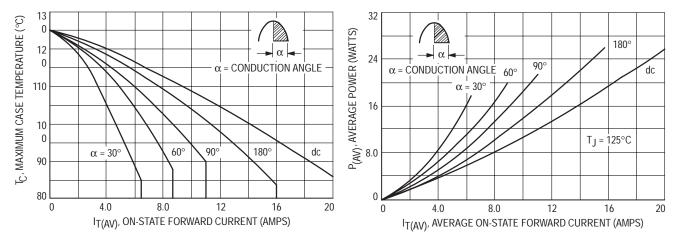
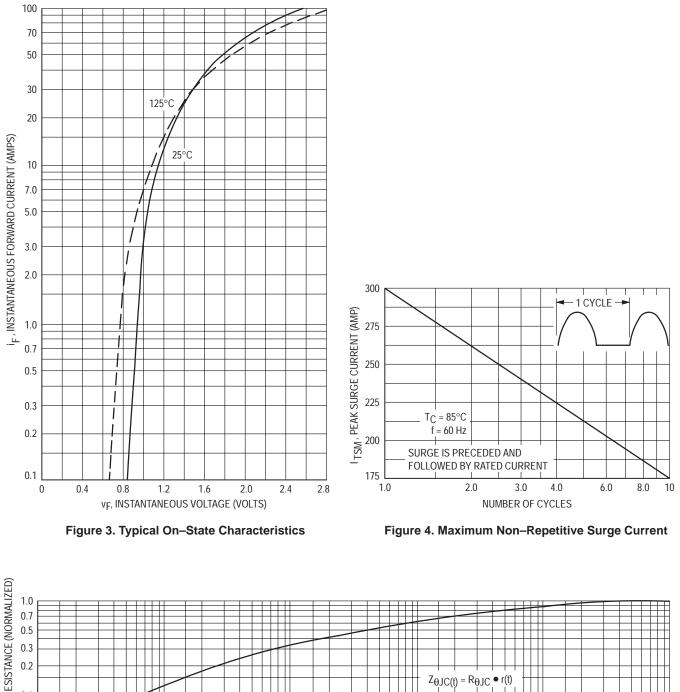


Figure 1. Average Current Derating

Figure 2. Maximum On–State Power Dissipation



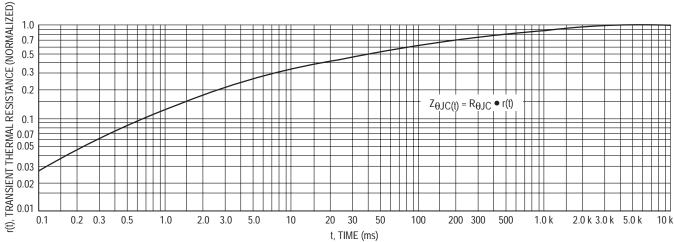


Figure 5. Thermal Response

TYPICAL TRIGGER CHARACTERISTICS

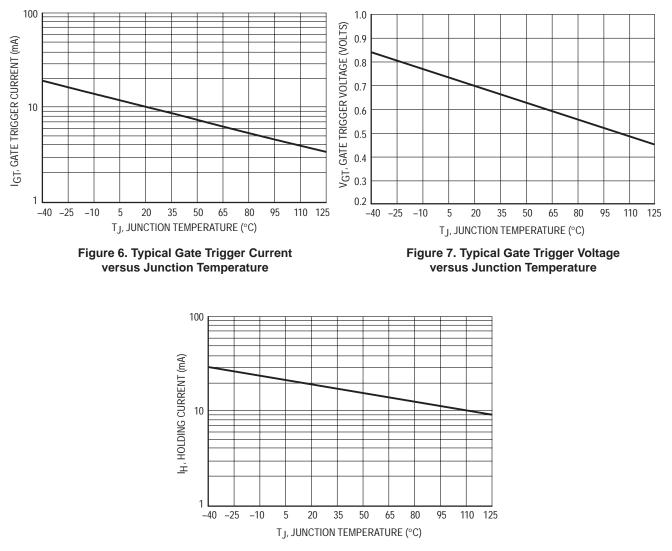
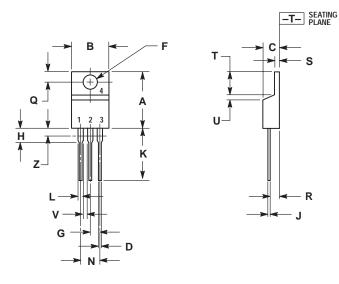


Figure 8. Typical Holding Current versus Junction Temperature

PACKAGE DIMENSIONS

TO-220AB CASE 221A-07 ISSUE Z



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.022	0.36	0.55	
К	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
Ν	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Ζ		0.080		2.04	

STYLE 3: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE

<u>Notes</u>

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